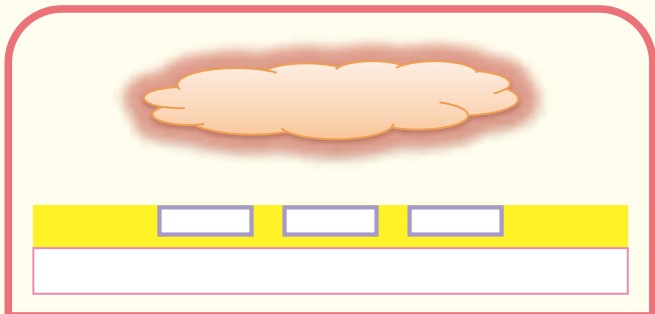


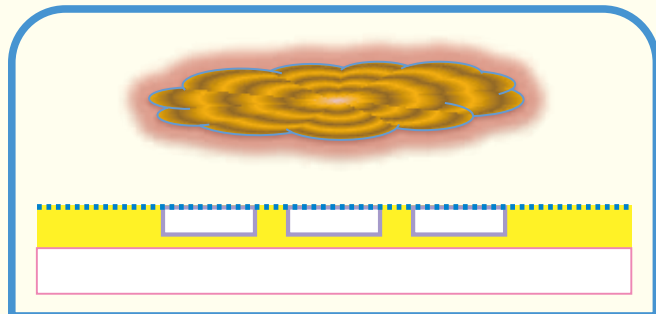
電極形成Cuメッキプロセス

Copper Plating Process

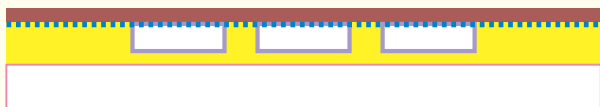
1 プラズマ処理 Plasma Treatment



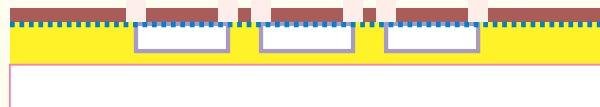
2 金属蒸着(シード層形成) Vapor Deposition of Seed Metal



3 メッキレジスト塗布※SIPR-7126 Photo Resist Coating



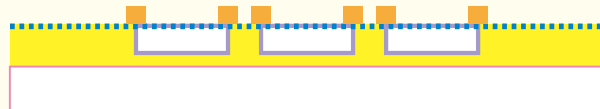
4 パターニング:露光・現像(TMAH水溶液) Photo Lithography



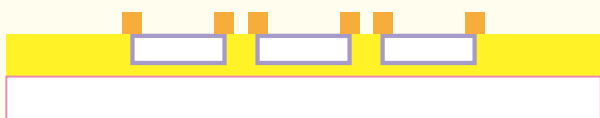
5 Cuメッキ 5~10 μ m (+Ag-Snメッキ) Cu Plating Deposition



6 レジスト剥離:PGMEA Resist Stripping



7 シード層剥離 Stripping of Metal Seed Layer



8 メッキ電極完成 Complete

